

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT																		
NATURE OF CONVEYANCE:	ASSIGNMENT																		
CONVEYING PARTY DATA																			
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Kuo-Chiang Ting	04/05/2012																		
RECEIVING PARTY DATA																			
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.																		
Street Address:	No. 8, Li-Hsin Road 6																		
Internal Address:	Science-Based Industrial Park																		
City:	Hsin-Chu																		
State/Country:	TAIWAN																		
Postal Code:	300-77																		
PROPERTY NUMBERS Total: 1																			
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13438451</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13438451														
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Application Number:	13438451																		
CORRESPONDENCE DATA																			
Fax Number:	(214)200-0853																		
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OP \$40.00 13438451

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ATTORNEY DOCKET NUMBER:

24061.2043/2011-1268

NAME OF SUBMITTER:

David M. O'Dell

Total Attachments: 4

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Docket No.: 2011-1268 / 24061.2043
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- (1) Jr Jung Lin of No. 21, Lane 495, Sec. 1, Jhongshan Road
Wurih Township, Taichung County 414, Taiwan, R.O.C.
- (2) Yun-Ju Sun of 17F-3, No. 16, Lane 167, Cheng-Gong Road, Sec. 4
Taipei 114, Taiwan, R.O.C.
- (3) Shih-Hsun Chang of F7-3, No. 15, Lane 175, Wu-Ling Road
Hsinchu, Taiwan, R.O.C.
- (4) Chia-Jen Chen of No. 182 Minchuan Road
Chiayi, Taiwan, R.O.C.
- (5) Tomonari Yamamoto of 40-14F, Juangjing 5th Street
Jhubei City, Hsinchu Country 302, Taiwan, R.O.C.
- (6) Chih-Wei Kuo of 3F, No. 8, Lane 257, Sec. 2, Room 2, Beimen Road, North District
Tainan 704, Taiwan, R.O.C.
- (7) Meng-Yi Sun of 9F, No. 6, Lane 37, Xinglong Road
Hsinchu Country, Hsinchu City, Taiwan, R.O.C.
- (8) Kuo-Chiang Ting of 12F-3, No. 90, Daxue Road
Hsinchu City 300, Taiwan, R.O.C.

have invented certain improvements in

STRUCTURE AND METHOD FOR MOSFETS WITH HIGH-K AND METAL GATE STRUCTURE

for which we have filed an application for Letters Patent of the United States of America on _____
April 3, 2012, and assigned U.S. Serial No. 13/438,451; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications

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thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Jr Jung Lin

Residence Address: No. 21, Lane 495, Sec. 1, Jhongshan Road
Wurih Township, Taichung County 414, Taiwan, R.O.C.

Dated: 2012. 4. 5

Lin Jr Jung
Inventor Signature

Inventor Name: Yun-Ju Sun



Residence Address: 17F-3, No. 16, Lane 167, Cheng-Gong Road, Sec. 4
Taipei 114, Taiwan, R.O.C.

Dated: 04/05/2012

Yun-Ju Sun
Inventor Signature

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Residence Address: F7-3, No. 15, Lane 175, Wu-Ling Road
Hsinchu, Taiwan, R.O.C.

Dated: 4/5/12  
Inventor Signature

Inventor Name: Chia-Jen Chen
Residence Address: No. 182 Minchuan Road
Chiayi, Taiwan, R.O.C.

Dated: 04/05/2012 
Inventor Signature

Inventor Name: Tomonari Yamamoto
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Inventor Name: Chih-Wei Kuo
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Dated: 孫向毅 2012/4/5

孫向毅 Meng-Yi Sun
Inventor Signature

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Residence Address: 12F-3, No. 90, Daxue Road
Hsinchu City 300, Taiwan, R.O.C.

Dated: 丁國強 2012/4/5

丁國強 Kuo-Chiang Ting
Inventor Signature